

Abstract

In the chip cards to be manufactured, integrated-circuit elements (chip 2 and/or electronic module 12), coupling means (coil 6, capacitor layers 8) for the non-contact transmission of electrical energy and/or data transfer, and at least one label (1) which forms an outer surface of the card are presupposed. The coupling means (6, 8) are applied to the inner surface of the said label. The label (1) thus prepared is then introduced into an injection mould. The separately furnished integrated-circuit elements (12) are then positioned in the injection mould to fit exactly over and to contact the terminals of the coupling means (6, 8). Finally, the body of the card is moulded and bonded to the label by an injection-moulding process and at the same time the integrated-circuit elements are embedded in the body of the card. Electrical connections between the coupling means (6, 8) and the integrated-circuit elements (12) are made in the mould itself by various means.

(Figure 3)